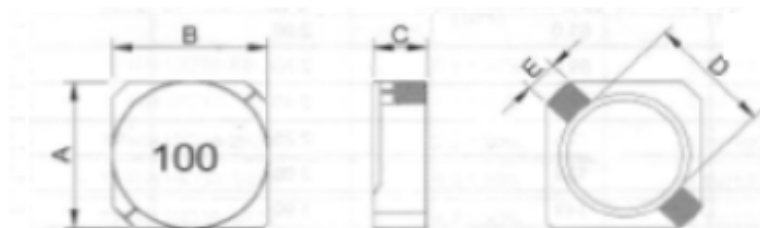


1. Features

- 1.Low profile very effective in space-conscious applications.
- 2.Low resistance and high energy storage.

2. Dimension



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
SSL3D16	4.0MAX	4.0MAX	1.9MAX	2.8REF	1.1REF

Units: mm

3. Part Numbering

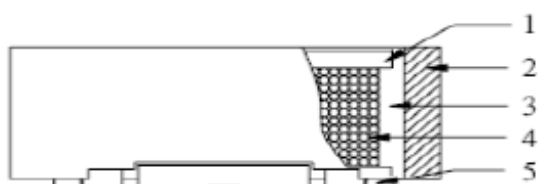


A:Series
 B:Dimension A xC
 C:Inductance
 D:Inductance Tolerance
 100=10uH
 M=± 20%, Y=± 30%

4.Specification

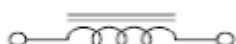
Part Number	Inductance (uH)	Test Frequency (Hz)	DCR (Ω) MAX	I _{rms} (A)	I _{sat} (A)
SSL3D16-3R3Y	3.3 ±30%	0.1V/100K	0.066	0.80	2.00
SSL3D16-3R9Y	3.9 ±30%	0.1V/100K	0.081	0.75	1.75
SSL3D16-4R7Y	4.7 ±30%	0.1V/100K	0.091	0.68	1.72
SSL3D16-5R6Y	3.9 ±30%	0.1V/100K	0.102	0.62	1.64
SSL3D16-6R8Y	6.8 ±30%	0.1V/100K	0.130	0.58	1.30
SSL3D16-8R2Y	8.2±30%	0.1V/100K	0.140	0.51	1.28
SSL3D16-100Y	10 ±30%	0.1V/100K	0.190	0.46	1.07
SSL3D16-120Y	12 ±30%	0.1V/100K	0.205	0.42	0.98
SSL3D16-150Y	15 ±30%	0.1V/100K	0.272	0.38	0.87
SSL3D16-180Y	18 ±30%	0.1V/100K	0.327	0.34	0.76
SSL3D16-220Y	22 ±30%	0.1V/100K	0.356	0.31	0.66
SSL3D16-270Y	27 ±30%	0.1V/100K	0.470	0.28	0.60
SSL3D16-330Y	33 ±30%	0.1V/100K	0.560	0.26	0.55
SSL3D16-390Y	39 ±30%	0.1V/100K	0.700	0.24	0.47
SSL3D16-470Y	47 ±30%	0.1V/100K	0.775	0.21	0.45

5.Material List

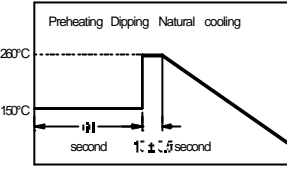
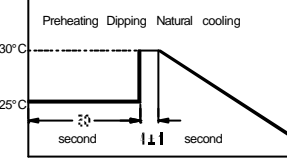


NO	ITEM	MATERIAL
1	CORE	FERRITE CORE (DR TYPE)
2	CORE	FERRITE CORE (RI TYPE)
3	GLUE	G500
4	WIRE	ENAMELLED COPPER WIRE
5	CLIP	SM212-032ET2N

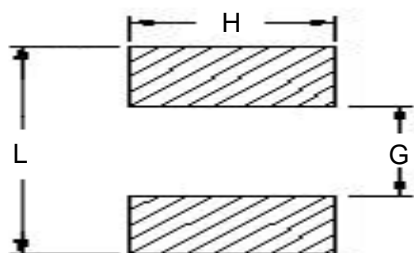
6. Schematic Diagram



7. Reliability and Test Condition

Item	Performance	Test Condition															
Operating Temperature	-20~+105																
Storage temperature	-40~+85																
Rated Current	Base on temp. rise & L/LOA=25% typ.																
Temperature Rise Test	40 max. (t)																
Solder heat Resistance	Appearance: No significant abnormality Inductance change: Within $\pm 20\%$.	 <p>Preheat:150 ,60sec. Solder : H63A Solder temperature:260 ±5 Flux: rosin Dip time:10 ±0.5sec.</p>															
Solderability	More than 90% of the terminal electrode should be covered with solder.	 <p>Preheat:125 ±5 ,60sec. Solder : H63A Solder temperature:230 ±5 Flux: rosin Dip time:4 ±1sec.</p>															
Thermal shock	Appearance: no damage. Inductance: within $\pm 20\%$ of initial value.	<table border="1" data-bbox="742 929 1045 1153"> <thead> <tr> <th>Phase</th> <th>Temperature()</th> <th>Time(min)</th> </tr> </thead> <tbody> <tr> <td>1</td> <td>-25 ±2</td> <td>30 ±3</td> </tr> <tr> <td>2</td> <td>Room Temp.</td> <td>15</td> </tr> <tr> <td>3</td> <td>+85 ±2</td> <td>30 ±3</td> </tr> <tr> <td>4</td> <td>Room Temp.</td> <td>15</td> </tr> </tbody> </table> <p>For SSL Condition for 1 cycle Step1:-25 ±2 30 ±3 min. Step2:Room temperature 15 min. Step3:+85 ±5 30 ±3 min. Step4: Room temperature 15 min. Number of cycles:50 Measured:50 times</p>	Phase	Temperature()	Time(min)	1	-25 ±2	30 ±3	2	Room Temp.	15	3	+85 ±2	30 ±3	4	Room Temp.	15
Phase	Temperature()	Time(min)															
1	-25 ±2	30 ±3															
2	Room Temp.	15															
3	+85 ±2	30 ±3															
4	Room Temp.	15															
Humidity Resistance Test	Appearance: no damage. Inductance: within $\pm 20\%$ of initial value.	Temperature:40 ±2 . Applied current:rated current. Duration:500 hrs. Humidity:90~95%															
High Temperature Resistance Test	Appearance: no damage. Inductance: within $\pm 20\%$ of initial value.	Temperature:85 ±2 . Applied current:rated current. Duration:500 hrs.															

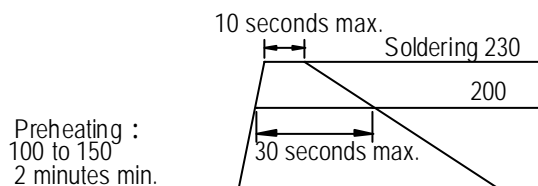
8. Recommended PC Board Pattern



L	G	H
5.2	2.4	1.5

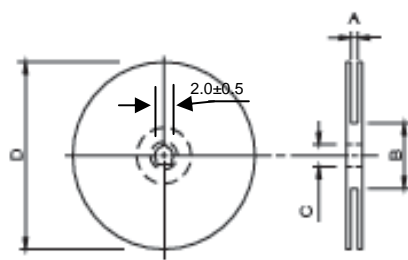
Units: mm

RECOMMENDED SOLDERING CONDITIONS REFLOW SOLDERINGS

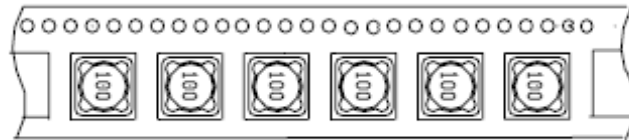
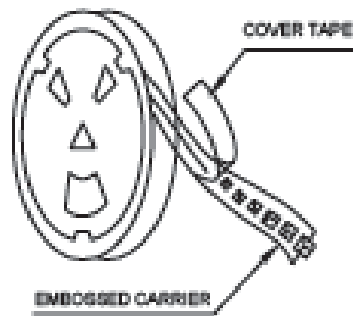


9. Packaging Information

9-1. Reel Dimension & Tape Dimension



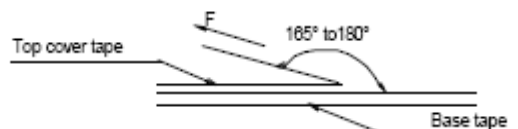
Type	A(mm)	B(mm)	C(mm)	(mm)
13x12m	12±0.5	100±1	13±0.2	330



9-2. Packaging Quantity

SSL	3D16
Chip / Reel	4000
Carton	32000
Reel Style	13"x12m

9-3. Tearing Off Force



The force for tearing off cover tape is 15 to 60 grams in the arrow direction under the following conditions.

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~65	860~1060	300

Application Notice

• Storage Conditions

To maintain the solderability of terminal electrodes:

1. Temperature and humidity conditions: Less than 40°C and 70% RH.
2. Recommended products should be used within 6 months from the time of delivery.
3. The packaging material should be kept where no chlorine or sulfur exists in the air.

• Transportation

1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
3. Bulk handling should ensure that abrasion and mechanical shock are minimized.